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E. Willis
5-10-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :
Kazuhiro OTSU ET AL :
Serial No. 10/067,370 : Attn: Office of Initial Patent
Examination Customer Service
Filed: February 7, 2002 : Center
Title: Separating machine for
thinned semiconductor substrate
And separation method

REQUEST FOR CORRECTED FILING RECEIPT

Assistant Commissioner for Patents,
Washington, D. C.

Sir:

Enclosed herewith is a copy of the Official Filing
Receipt for the above-identified application marked in
red indicating corrections to be made thereto.

Accordingly, it is requested that the PTO issue a
Corrected Filing Receipt reflecting these corrections.

Respectfully submitted,

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April 18, 2002

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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
10/067,370	02/07/2002	2812	740	2002-0208A	2	9	2

CONFIRMATION NO. 7449

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Date Mailed: 04/08/2002

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

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Domestic Priority data as claimed by applicant

Foreign Applications

JAPAN 30746/01 02/07/2001

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Title

Separating machine for thinned semiconductor substrate and separation method

Preliminary Class

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SEPARATION